



Diameter Size: 20 mm
 Thickness: 1,6 mm
 Weight: 1 g
 Electricity Line: Copper
 Thickness of copper: 35um
 Thickness of the dielectric: 70um
 Thickness of the aluminum-base: 1.5mm

Lenses for PCB 724-30:



The result of the test:

Item	Test item	Technology request	Unit	Test result
1	Peel Strength	≥ 1.8	N/mm	2.0
	After thermal stress (260°C)	≥ 1.8	N/mm	1.8
2	Blister test After Thermal stress (288°C , 2min)	288°C, 2 min No delaminating	/	Ok
3	Thermal resistance	≤ 2.0	°C/W	1.0
4	Thermal-Conductive Factor		W/m-k	1.0
5	Flammability(A)	FV-O	/	FV-O
6	Surface Resistivity	$\geq 1 \times 10^5$	MΩ	5×10^7
	Constant humidity treatment (90%,35°C,96h)	$\geq 1 \times 10^5$	MΩ	2×10^6
7	Volume Resistivity	$\geq 1 \times 10^6$	MΩ-m	4×10^8
	Constant humidity treatment (90%,35°C,96h)	$\geq 1 \times 10^6$	MΩ-m	5×10^7
8	Dielectric Breakdown(DC)	≥ 28.5	KV/MM	31
9	Dielectric constant(1MHz) (40°C, 93%, 96h)	≤ 4.4	/	4.2
10	Dielectric dissipation factor (1MHz) (40°C , 93% , 96h)	≤ 0.03	/	0.02

